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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant(s): MASUDA, et al  
Serial No.: (not yet assigned)  
Filed: August 26, 2003  
For: PLASMA ETCHING APPARATUS AND PLASMA ETHCING  
METHOD

**REAFFIRMATION OF CLAIM FOR PRIORITY**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

August 26, 2003

Sir:

Under the provisions of 35 USC §119 and 37 CFR §1.55, Applicants hereby claim the right of priority based on Japanese Patent Application No. 7-057472, filed in Japan on March 15, 1995.

The certified copy of the above-referred to Japanese Patent Application was filed on May 28, 1996 in prior application 08/611,758, filed March 8, 1996.

Respectfully submitted,



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